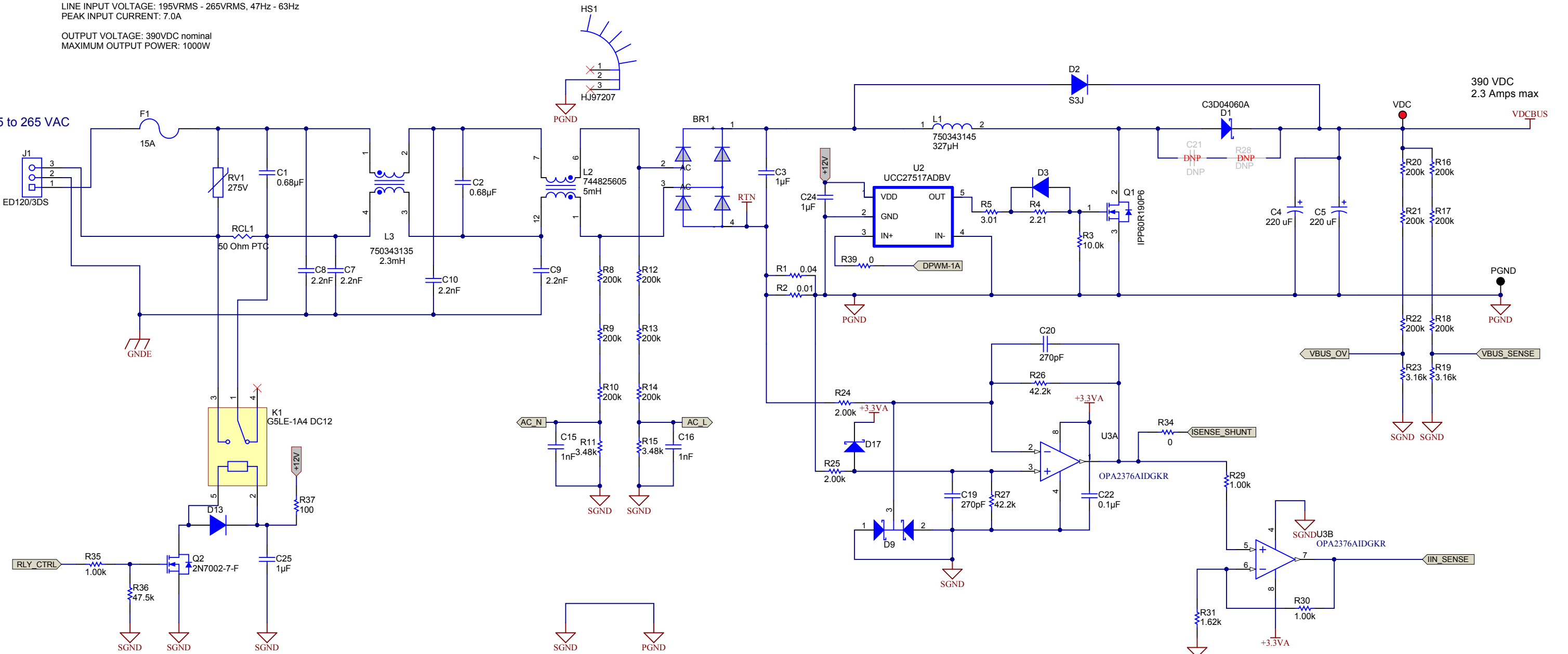


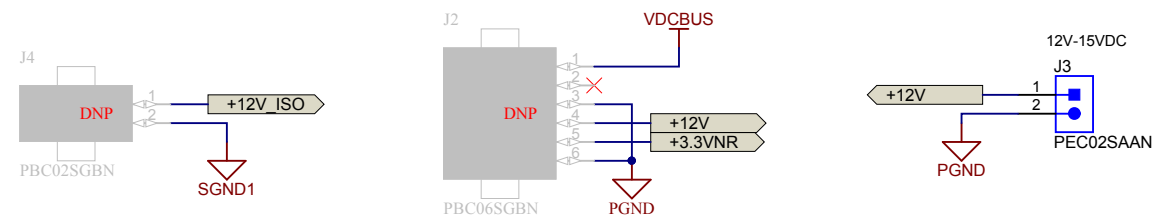
NOTES:
 LINE INPUT VOLTAGE: 195VRMS - 265VRMS, 47Hz - 63Hz
 PEAK INPUT CURRENT: 7.0A

OUTPUT VOLTAGE: 390VDC nominal
 MAXIMUM OUTPUT POWER: 1000W

195 to 265 VAC

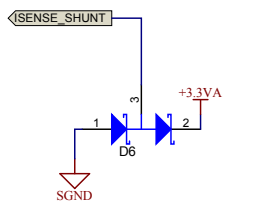
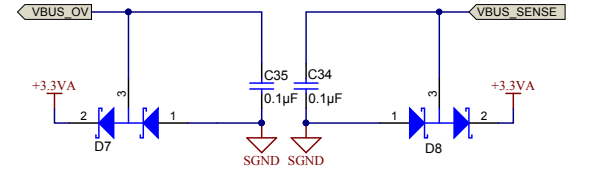
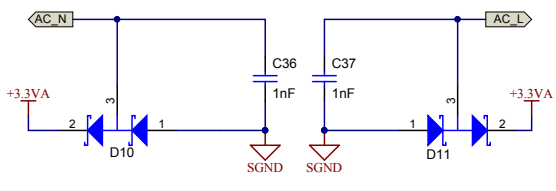
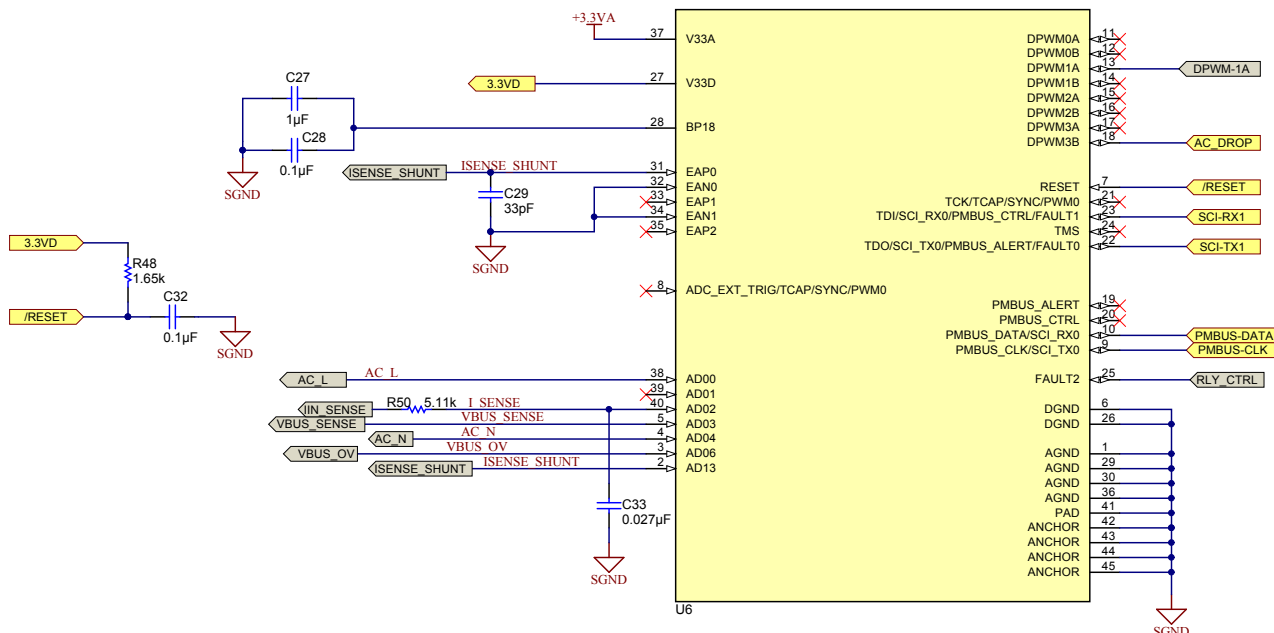
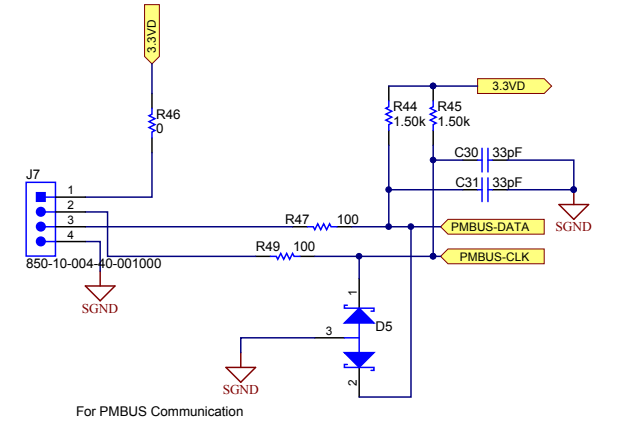
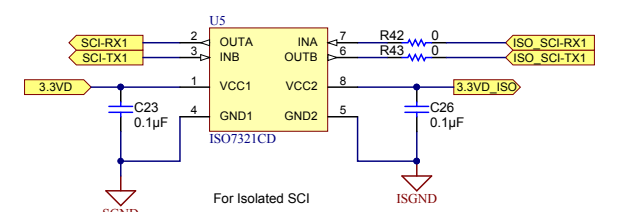
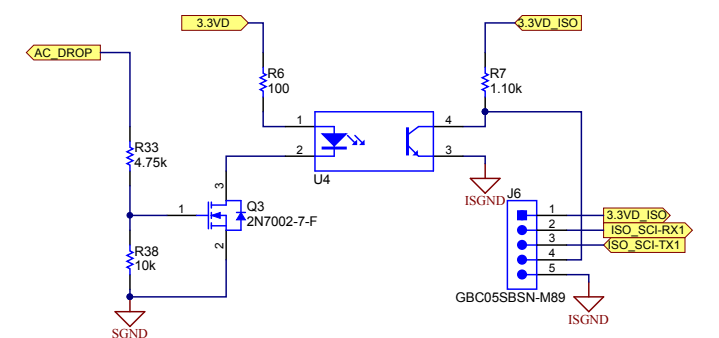
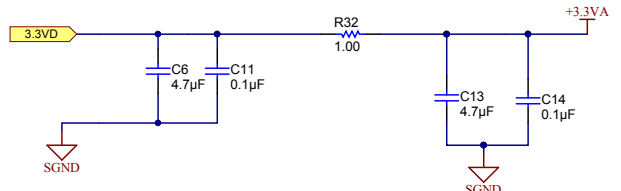
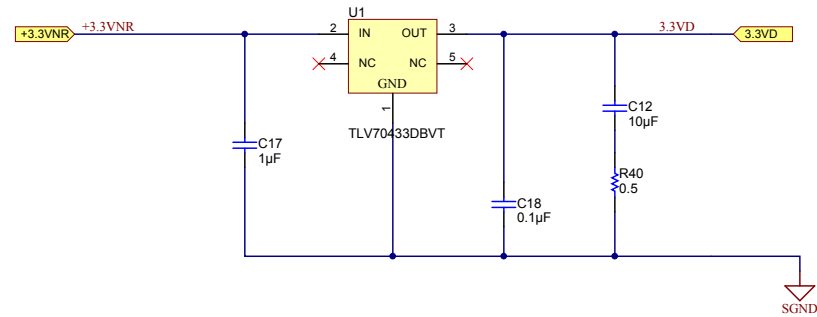


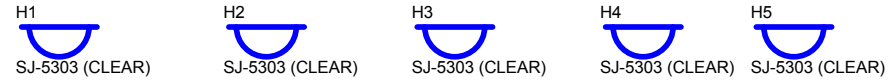
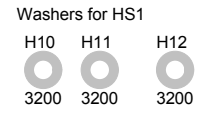
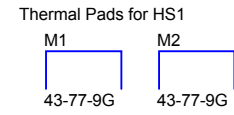
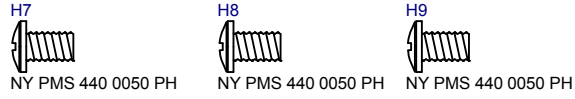
NTC BYPASS CIRCUIT



Orderable: N/A	Designed for: Public Release	Mod. Date: 3/17/2016
TID #: TIDA-00707	Project Title: 1kW Digital PFC Converter	
Number: TIDA-00707	Rev: E1	Sheet Title:
SVN Rev: Not in version control	Assembly Variant: 001	Sheet: 1 of 3
Drawn By:	File: Power_SchDoc	Size: B
Engineer: Dora Krishna	Contact: http://www.ti.com/support	

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PCB Number: TIDA-00707
PCB Rev: E1

PCB
LOGO
Texas Instruments

PCB
LOGO
Pb-Free Symbol

Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Orderable: N/A	Designed for: Public Release	Mod. Date: 3/17/2016
TID #: TIDA-00707	Project Title: 1kW Digital PFC Converter	
Number: TIDA-00707	Rev: E1	Sheet Title:
SVN Rev: Not in version control	Assembly Variant: 001	Sheet: 3 of 3
Drawn By:	File: TID_Hardware.SchDoc	Size: B
Engineer: Dora Krishna	Contact: http://www.ti.com/support	

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